

Dr. Xiaoxiong (Kevin) Gu received his Ph.D. in Electrical Engineering from the University of Washington in 2006. He joined IBM T. J. Watson Research Center as a Research Staff Member in January 2007. His research activities are focused on Signal and Power Integrity with emphasis on 5G radio access technologies, optoelectronic and mm-wave packaging, electrical designs, modeling and characterization of communication and computation systems. He has also worked on 3D electrical packaging and EMC analysis for high-speed I/O subsystems including on-chip and off-chip interconnects. He has been involved in developing novel TSV and interposer technologies for heterogeneous system integration. He also has extensive experience in antenna-in-package design and integration for mm-wave imaging and communication systems including Ka-band, V-band and W-band phased-array modules.

Dr. Gu has authored and co-authored over 80 IEEE Transactions/Conference papers and has nine issued patents. He was the co-recipient of ISSCC 2017 Lewis Winner Award for Outstanding Paper (the world's first reported silicon-based 5G mmWave phased array antenna module operating at 28 GHz). He also received an IBM Outstanding Technical Achievement Award in 2016, four IBM Plateau Invention Awards in 2012 ~ 2016, the IEEE EMC Symposium Best Paper Award in 2013, two SRC Mahboob Khan Outstanding Industry Liaison Awards in 2012 and 2014, the Best Conference Paper Award at IEEE EPEPS in 2011, IEC DesignCon Paper Awards in 2008 and 2010, the Best Interactive Session Paper Award at IEEE in 2008, and the Best Session Paper Award at IEEE ECTC in 2007. Dr. Gu was also the general chair of IEEE 2018 EPEPS Conference. Dr. Gu is the co-chair of Professional Interest Community (PIC) on Computer System Designs at IBM. He is a Senior Member of IEEE and has been serving on the technical program committees for IMS, EPEPS, ECTC, EDAPS and DesignCon.